

### Abstract

The invention relates to the manufacturing of permanent connections in producing the equipment based on microelectronics components and semiconductor devices, and particularly to contact nodes by which the assembling, including the assembling of multilayered connection plates for the multichip modules (MCM) as well as the mounting of LSIC chips in manufacturing the MCM are performed. The contact node comprises at least two metallized contacts coupled with conductive paths (2, 6) arranged on surfaces of connection layers (3, 7) made on the base of a dielectric material and mutually aligned and interconnected electrically and mechanically by conductive binding material (8). The contact node is a joint between a contact made in the form of a metallized pad (1) coupled with a the conductive paths (2) on the surface of the underlying connection layer (3) and a respective contact made in the form of a metallized hole (4) in a dielectric material layer.